

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4556	nickel near2 alloy and copper and (V or Cr or Al or Si or Ti) and ('solder' 'bump') and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/22 15:40
L2	2537	!1 and @pd<="20041014"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/22 15:42
L3	443962	!2 and (copper adj solder) or (Pb-Sn solder) or (Sn solder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/22 17:14
L4	2384	!2 and ((copper adj solder) or (Pb-Sn solder) or (Sn solder))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/22 17:14
L5	2119	!1 and @pd<="20031014"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/22 17:14
L6	2125	!1 and @pd<="20031024"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/22 17:15
L7	2019	!6 and ((copper adj solder) or (Pb-Sn solder) or (Sn solder))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/22 17:15
L8	992	!7 and (("257"/\$.cds.) or ("438"/\$.cds.))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/22 17:16
L9	1683	257/780.cds.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/22 17:49

L10	2869	257/737.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/22 17:50
L11	2351	257/738.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/22 17:50
L12	564	257/772.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/22 17:50
L13	1354	257/779.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/22 17:50
L14	449	257/e23.015.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/22 17:56
L15	2233	257/e23.02.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/22 17:56
L16	268	257/e23.023.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/22 17:56
S1	6780	nickel near2 alloy and ('solder' 'bump') and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/10 17:24
S2	2296	('nickel adj cooper' 'Ni-Cu' 'NiCu')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/10 17:25
S3	51	S1 and S2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/10 17:25

S4	6577	Sn near2 solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/10 17:25
S5	9	S3 and S4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/10 17:26
S6	495	257/616.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/22 14:20

5/22/08 5:59:20 PM

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